



General Information





Style SMD Chip Description SMD, MLCC, Temperature Stable, Class II Features Temperature Stable, Class II RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 21 mg		
Description SMD, MLCC, Temperature Stable, Class II Features Temperature Stable, Class II RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 78 Weeks	Series	SMD Comm X5R
Stable, Class II Features Temperature Stable, Class II RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 21 mg Shelf Life 78 Weeks	Style	SMD Chip
RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 21 mg Shelf Life 78 Weeks	Description	
Termination Tin Marking No AEC-Q200 No Typical Component Weight 21 mg Shelf Life 78 Weeks	Features	Temperature Stable, Class II
Marking No AEC-Q200 No Typical Component Weight 21 mg Shelf Life 78 Weeks	RoHS	Yes
AEC-Q200 No Typical Component Weight 21 mg Shelf Life 78 Weeks	Termination	Tin
Typical Component Weight 21 mg Shelf Life 78 Weeks	Marking	No
Shelf Life 78 Weeks	AEC-Q200	No
	Typical Component Weight	21 mg
MSL 1	Shelf Life	78 Weeks
	MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	1.25mm +/-0.15mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

Specifications	
Capacitance	4.7 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	6.3 VDC
Dielectric Withstanding Voltage	15.75 VDC
Temperature Range	-55/+85°C
Temp. Coefficient	X5R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	10% 1 kHz 1.0Vrms
Aging Rate	5% Loss/Decade Hour: Referee Time is 48 Hours
Insulation Resistance	21.3 MOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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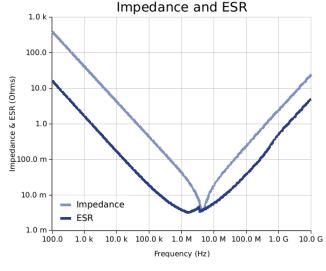


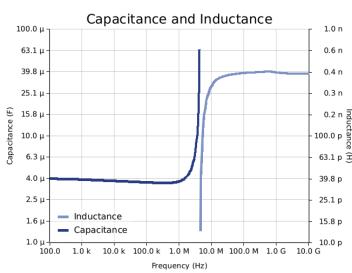


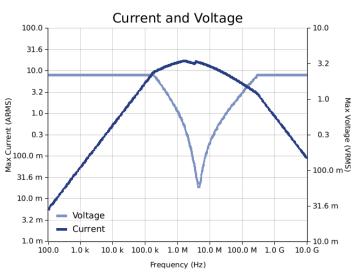
SMD Comm X5R, Ceramic, 4.7 uF, 10%, 6.3 VDC, X5R, SMD, MLCC, Temperature Stable, Class II, 0805, 0.7 mm

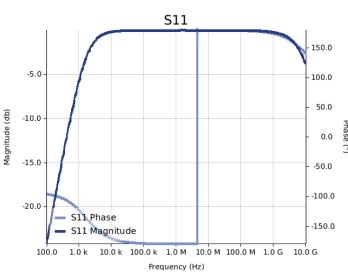
Simulations

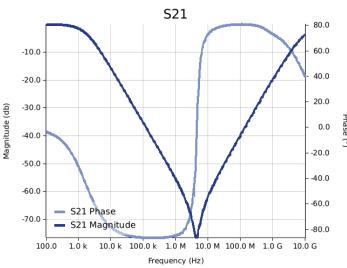
For the complete simulation environment please visit K-SIM.

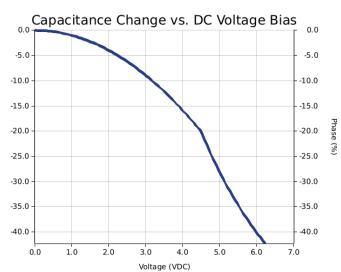












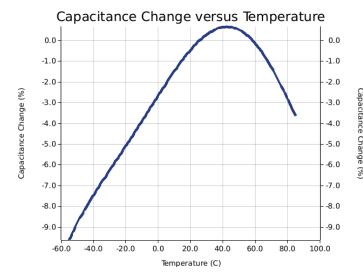
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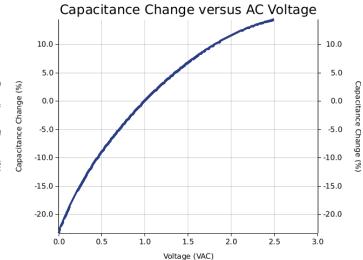
Phase (%)



C0805C475K9PAC7210

SMD Comm X5R, Ceramic, 4.7 uF, 10%, 6.3 VDC, X5R, SMD, MLCC, Temperature Stable, Class II, 0805, 0.7 mm





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C0805C475K9PAC7210

SMD Comm X5R, Ceramic, 4.7 uF, 10%, 6.3 VDC, X5R, SMD, MLCC, Temperature Stable, Class II, 0805, 0.7 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.

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